

# H-putty

## Thermal Conductive Putty

LiPOLY H-putty is a one-part dispensable material with thermal conductivity 3.5 W/m\*K. High deformation can fill small air gaps perfectly to remove tolerance. It can also overcome spillage and drying issues to increase thermal conductivity, making it ideal for dispensing with dispensing robots.

### ■ FEATURES

- / Thermal conductivity:3.5 W/m\*K
- / Bond line thickness:100-3000μm
- / Designed to remove manufacturing tolerances
- / Does not produce stress on delicate components
- / No vertical flow
- / Dispensable for serial manufacture
- / For any high compression and low stress application

### ■ TYPICAL APPLICATION

- / Between CPU and heat sink
- / Between a component and heat sink
- / High speed mass storage drives
- / Telecommunication hardware
- / Flat-panel displays
- / Set-top box
- / IP CAM
- / 5G base station & infrastructure
- / EV electric vehicle

### ■ CONFIGURATIONS

- / Cartridges: 30ml, 55ml, 330ml
- / Bucket: 1kg, 25kg

### ■ PRESERVATION

It can be preserved for 60 months under the condition of unopened and under room temperature 25°C.

### ■ TYPICAL PROPERTIES

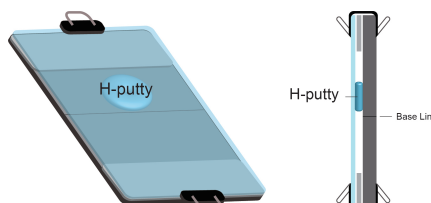
PROPERTY	H-putty	TEST METHOD	UNIT
Color	Blue	Visual	-
Resin base	Silicone	-	-
Viscosity	15000	DIN 53018	Pa.s
Density	3.0	ASTM D792	g/cm <sup>3</sup>
Application temperature	-60~180	-	°C
Bond line thickness	100~3000	-	μm
Shelf life	60 months	-	-
ROHS & REACH	Compliant	-	-
ELECTRICAL			
Dielectric breakdown	12	ASTM D149	KV/mm
Volume resistivity	>10 <sup>13</sup>	ASTM D257	Ohm-m
THERMAL			
Thermal conductivity	3.5	ASTM D5470	W/m*K
Thermal impedance@10psi / 60°C	0.076	ASTM D5470	°C-in <sup>2</sup> / W
Thermal impedance@30psi / 60°C	0.072	ASTM D5470	°C-in <sup>2</sup> / W
Thermal impedance@50psi / 60°C	0.069	ASTM D5470	°C-in <sup>2</sup> / W

### ■ PLEASE NOTE

- / Using Automatic Homogenizer can improve the sedimentation phenomenon rapidly to achieve a homogeneous effect. We strongly recommend put cartridge in homogenizer for 3~5 minutes before dispensing the material.
- Notice: if material homogenized more than 24 hours, it must be homogenized again while use it.

### ■ VERTICAL RELIABILITY

Using 3.0mm pad as a gap control, put the putty between the aluminum and the glass panel mark the initial position. Then, place it in the oven with 125°C for 1,000 hours and observe its displacement after reliability test



Material no dropped or changed after high temperature aging testing

